1. Record Nr. UNINA9911006982203321 Autore Wasa Kiyotaka **Titolo** Thin film materials technology: sputtering of compound materials // by Kiyotaka Wasa, Makoto Kitabatake, Hideaki Adachi Norwich, NY,: William Andrew Pub. Pubbl/distr/stampa Heidelberg, : Springer, c2004 **ISBN** 1-282-02766-2 9786612027666 0-08-094698-4 0-8155-1931-1 Descrizione fisica 1 online resource (533 p.) Altri autori (Persone) KitabatakeMakoto AdachiHideaki Disciplina 621.3815/2 Soggetti Cathode sputtering (Plating process) Thin films Lingua di pubblicazione Inglese **Formato** Materiale a stampa Livello bibliografico Monografia Note generali Description based upon print version of record. Includes bibliographical references and index. Nota di bibliografia Nota di contenuto Front Cover; Thin Film Materials Technology: Sputtering of Compound Materials; Copyright Page; Table of Contents; Chapter 1. Thin Film Materials and Devices; 1.1 THIN FILM MATERIALS; 1.2 THIN FILM DEVICES; REFERENCES; Chapter 2. Thin Film Processes; 2.1 THIN FILM GROWTH PROCESS: 2.2 THIN FILM DEPOSITION PROCESS: 2.3 CHARACTERIZATION; REFERENCES; Chapter 3. Sputtering Phenomena; 3.1 SPUTTER YIELD; 3.2 SPUTTERED ATOMS; 3.3 MECHANISMS OF SPUTTERING: REFERENCES: Chapter 4. Sputtering Systems: 4.1 DISCHARGE IN A GAS; 4.2 SPUTTERING SYSTEMS; 4.3 PRACTICAL

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## Sommario/riassunto

An invaluable resource for industrial science and engineering newcomers to sputter deposition technology in thin film production applications, this book is rich in coverage of both historical developments and the newest experimental and technological information about ceramic thin films, a key technology for nanomaterials in high-speed information applications and large-area functional coating such as automotive or decorative painting of plastic parts, among other topics. In seven concise chapters, the book thoroughly reviews basic thin film technology and deposition processes, sputtering pro